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 NEWS 3 SEP 09 CA/CAPLUS records now contain indexing from 1907 to the present  
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 NEWS 14 OCT 21 BIOSIS file reloaded and enhanced  
 NEWS 15 OCT 28 BIOSIS file segment of TOXCENTER reloaded and enhanced

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```
=> s phenol novolak resin#
L1      1107 PHENOL NOVOLAK RESIN#

=> s crude and l1
L2      83 CRUDE AND L1

=> s 12 and ortho
L3      11 L2 AND ORTHO

=> s 13 and catalyst# and (sulfuric or benzenesulfonic or toluenesulfonic)
L4      4 L3 AND CATALYST# AND (SULFURIC OR BENZENESULFONIC OR TOLUENESUL
        FONIC)

=> d 14 1-4
```

L4 ANSWER 1 OF 4 EUROPATEFULL COPYRIGHT 2003 WILA on STN

Full  
Text

PATENT APPLICATION - PATENTANMELDUNG - DEMANDE DE BREVET

```
AN      1275673 EUROPATEFULL ED 20030127 EW 200303 FS OS
TIEN    Epoxy resin composition, cured article thereof, novel epoxy resin, novel
        phenol compound, and process for preparing the same.
TIDE    Epoxidharzzusammensetzung, daraus hergestellter gehaertete Gegenstand,
        neues Epoxidharz, neue Phenolverbindung, und Verfahren zu deren
        Herstellung.
TIFR    Composition de resine epoxy, article reticule, nouvelle resine epoxy,
        nouveau compose phenolique et procede de preparation.
IN      Ogura, Ichiro, 614-56, Iriyamazu, Ichihara-shi, Chiba-ken, JP;
        Takahashi, Yoshiyuki, 3-46-28, Chiharadai, Ichihara-shi, Chiba-ken, JP;
        Imada, Tomoyuki, 3-27-6-107, Tatsumidai-higashi, Ichihara-shi,
        Chiba-ken, JP
PA      DAINIPPON INK AND CHEMICALS, INC., 35-58, Sakashita 3-chome, Itabashi-ku
        Tokyo, JP
SO      Wila-EPZ-2003-H03-T1a
DS      R AT; R BE; R BG; R CH; R CY; R CZ; R DE; R DK; R EE; R ES; R FI; R FR;
        R GB; R GR; R IE; R IT; R LI; R LU; R MC; R NL; R PT; R SE; R SK; R TR;
        R AL; R LT; R LV; R MK; R RO; R SI
PIT     EPA2 EUROPATISCHE PATENTANMELDUNG
PI      EP 1275673          A2 20030115
OD      20030115
AI      EP 2002-14977      20020709
PRAI    JP 2001-2001212069 20010712
        JP 2001-2001326305 20011024
IC      ICM C08G059-00
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L4 ANSWER 2 OF 4 USPATFULL on STN

Full  
Text

```
AN      2003:134763 USPATFULL
TI      Epoxy resin composition, cured article thereof, novel epoxy resin, novel
        phenol compound, and process for preparing the same
IN      Ogura, Ichiro, Ichihara-shi, JAPAN
        Takahashi, Yoshiyuki, Ichihara-shi, JAPAN
        Imada, Tomoyuki, Ichihara-shi, JAPAN
PA      Dainippon Ink and Chemicals, Inc., Tokyo, JAPAN (non-U.S. corporation)
PI      US 2003092852      A1 20030515
AI      US 2002-190491      A1 20020709 (10)
PRAI    JP 2001-212069      20010712
        JP 2001-326305      20011024
DT      Utility
FS      APPLICATION
```

LN.CNT 904  
 INCL INCLM: 525/403.000  
 INCLS: 549/200.000  
 NCL NCLM: 525/403.000  
 NCLS: 549/200.000  
 IC [7]  
 ICM: C07D321-00  
 ICS: C08G065-32  
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L4 ANSWER 3 OF 4 USPATFULL on STN

Full Text	Citing References
AN 2002:172464 USPATFULL	
TI Method of producing novolak resin	
IN Saito, Noriaki, Toyonaka-shi, JAPAN	
Aizu, Ichishi, Niihama-shi, JAPAN	
Nakajima, Nobuyuki, Niihama-shi, JAPAN	
Fujiwara, Masahiro, Niihama-shi, JAPAN	
Yano, Koji, Niihama-shi, JAPAN	
PA SUMITOMO CHEMICAL COMPANY, LIMITED (non-U.S. corporation)	
PI US 2002091224	A1 20020711
AI US 2001-364	A1 20011204 (10)
PRAI JP 2000-377258	20001212
JP 2000-377259	20001212
JP 2001-153632	20010523
DT Utility	
FS APPLICATION	
LN.CNT 579	
INCL INCLM: 528/129.000	
NCL NCLM: 528/129.000	
IC [7]	
ICM: C08G008-04	
CAS INDEXING IS AVAILABLE FOR THIS PATENT.	

L4 ANSWER 4 OF 4 USPATFULL on STN

Full Text	Citing References
AN 1998:4379 USPATFULL	
TI Positive resin composition sensitive to ultraviolet rays	
IN Kawabe, Yasumasa, Haibara-gun, Japan	
Yamanaka, Tsukasa, Haibara-gun, Japan	
Aoi, Toshiaki, Haibara-gun, Japan	
PA Fuji Photo Film Co., LTD., Kanagawa, Japan (non-U.S. corporation)	
PI US 5707776	19980113
AI US 1995-438481	19950510 (8)
PRAI JP 1994-98671	19940512
DT Utility	
FS Granted	
LN.CNT 1881	
INCL INCLM: 430/270.100	
INCLS: 430/920.000; 430/921.000; 430/905.000; 430/171.000; 430/176.000;	
522/166.000	
NCL NCLM: 430/270.100	
NCLS: 430/171.000; 430/176.000; 430/905.000; 430/920.000; 430/921.000;	
522/166.000	
IC [6]	
ICM: G03C001-73	
EXF 430/270; 430/920; 430/921; 430/905; 430/171; 430/176; 522/166	
CAS INDEXING IS AVAILABLE FOR THIS PATENT.	

=> s phenol# and (aldehyde or formaldehyde) and pressure

L5 59271 PHENOL# AND (ALDEHYDE OR FORMALDEHYDE) AND PRESSURE

=> s 15 and heat# and condenser  
L6 5830 L5 AND HEAT# AND CONDENSER

=> s 16 and reflux?  
L7 4419 L6 AND REFLUX?

=> s 17 and ortho  
L8 1151 L7 AND ORTHO

=> s 18 and phenol novolak resin#  
L9 6 L8 AND PHENOL NOVOLAK RESIN#

=> d 19 1-6

L9 ANSWER 1 OF 6 EUROPATFULL COPYRIGHT 2003 WILA on STN

Full  
Text

PATENT APPLICATION - PATENTANMELDUNG - DEMANDE DE BREVET

AN 435502 EUROPATFULL ED 20000813 EW 199127 FS OS STA B  
TIEN Method of preparing high glass transition temperature novolak resins  
useful in high resolution photoresist compositions.  
TIDE Verfahren zur Herstellung von Novolakharzen mit hoher  
Glasuebergangstemperatur, verwendbar bei lichtempfindlichen  
Fotowiderstand-Harzzusammensetzungen mit hoher Aufloesung.  
TIFR Procede de preparation d'une resine novolaque a haute temperature de  
transition vitreuse utilisable pour des compositions d'agents  
photoresistants a haute resolution.  
IN Bogan, Leonard Edward, Jr., 325 Moyer Road, Harleysville, Pennsylvania  
19438, US  
PA ROHM AND HAAS COMPANY, Independence Mall West, Philadelphia Pennsylvania  
19105, US  
SO Wila-EPZ-1991-H27-T1  
DS R AT; R BE; R CH; R DE; R DK; R ES; R FR; R GB; R GR; R IT; R LI; R LU;  
R NL; R SE  
PIT EPA1 EUROPAEISCHE PATENTANMELDUNG  
PI EP 435502 A1 19910703  
OD 19910703  
AI EP 1990-313404 19901210  
PRAI US 1989-452027 19891218  
IC ICM C08G008-24  
ICS G03F007-023 C08G008-08

L9 ANSWER 2 OF 6 EUROPATFULL COPYRIGHT 2003 WILA on STN

Full  
Text

GRANTED PATENT - ERTEILTES PATENT - BREVET DELIVRE

AN 219928 EUROPATFULL ED 20020307 EW 199218 FS PS STA B  
TIEN Epoxy fluorocarbon coating composition and process to make same.  
TIDE Ueberzugsmittelzusammensetzung aus Epoxidharzen und Fluorcarbonpolymeren  
und Verfahren zu deren Herstellung.  
TIFR Composition de revetement a base d'une resine epoxyde et d'un polymere  
fluorocarbone et procede de preparation de cette composition.  
IN Giordano, Paul J., 5595 Hummelfine Drive, Hudson Ohio, US;  
Smierciak, Richard C., 9285 June Drive, Streetsboro Ohio, US  
PA THE STANDARD OIL COMPANY, 200 Public Square, 36-F-3454, Cleveland Ohio  
44114, US  
SO Wila-EPS-1992-H18-T1  
DS R DE; R FR; R GB  
PIT EPB1 EUROPAEISCHE PATENTSCHRIFT

PI	EP 219928	B1	19920429	
OD			19870429	
AI	EP 1986-305599		19860722	
PRAI	US 1985-777890		19850919	
	US 1986-856625		19860425	
REP	DE 1519010 A	DE	2122408	A
	DE 2264132 A	FR	2396785	A
	US 2777783 A	US	3023189	A
IC	ICM C09D163-00			
	ICS C08L063-00			

L9 ANSWER 3 OF 6 USPATFULL on STN

Full Text	Citing References
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AN 2002:172464 USPATFULL  
 TI Method of producing novolak resin  
 IN Saito, Noriaki, Toyonaka-shi, JAPAN  
 Aizu, Ichishi, Niihama-shi, JAPAN  
 Nakajima, Nobuyuki, Niihama-shi, JAPAN  
 Fujiwara, Masahiro, Niihama-shi, JAPAN  
 Yano, Koji, Niihama-shi, JAPAN  
 PA SUMITOMO CHEMICAL COMPANY, LIMITED (non-U.S. corporation)  
 PI US 2002091224 A1 20020711  
 AI US 2001-364 A1 20011204 (10)  
 PRAI JP 2000-377258 20001212  
 JP 2000-377259 20001212  
 JP 2001-153632 20010523  
 DT Utility  
 FS APPLICATION  
 LN.CNT 579  
 INCL INCLM: 528/129.000  
 NCL NCLM: 528/129.000  
 IC [7]  
 ICM: C08G008-04  
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L9 ANSWER 4 OF 6 USPATFULL on STN

Full Text	Citing References
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AN 93:44346 USPATFULL  
 TI Phenolic resin and method for preparing same  
 IN Ando, Shinji, Nagoya, Japan  
 Fukui, Yukio, Nagoya, Japan  
 Imuro, Shigeru, Nagoya, Japan  
 PA Mitsui Toatsu Chemicals, Inc., Tokyo, Japan (non-U.S. corporation)  
 PI US 5216112 19930601  
 AI US 1991-745422 19910815 (7)  
 PRAI JP 1990-216984 19900820  
 JP 1990-216985 19900820  
 JP 1990-262984 19901002  
 JP 1991-39940 19910306  
 DT Utility  
 FS Granted  
 LN.CNT 951  
 INCL INCLM: 528/157.000  
 INCLS: 528/129.000; 528/144.000; 528/165.000  
 NCL NCLM: 528/157.000  
 NCLS: 528/129.000; 528/144.000; 528/165.000  
 IC [5]  
 ICM: C08G008-04  
 ICS: C08G014-04  
 EXF 528/129; 528/165; 528/144; 528/157  
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L9 ANSWER 5 OF 6 USPATFULL on STN

Full Text	Citing References
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AN 91:30357 USPATFULL  
 TI Epoxy fluorocarbon coating compositions and the process to make the same  
 IN Giordano, Paul J., Hudson, OH, United States  
 Smierciak, Richard C., Streetsboro, OH, United States  
 PA The Standard Oil Company, Cleveland, OH, United States (U.S. corporation)  
 PI US 5008135 19910416  
 AI US 1990-554933 19900718 (7)  
 RLI Continuation of Ser. No. US 1989-334736, filed on 7 Apr 1989, now abandoned which is a continuation of Ser. No. US 1988-186673, filed on 21 Apr 1988, now abandoned which is a continuation of Ser. No. US 1986-856625, filed on 25 Apr 1986, now abandoned which is a continuation-in-part of Ser. No. US 1985-777890, filed on 19 Sep 1985, now abandoned  
 DT Utility  
 FS Granted  
 LN.CNT 781  
 INCL INCLM: 427/386.000  
 INCLS: 523/169.000; 523/435.000; 525/113.000; 525/121.000  
 NCL NCLM: 427/386.000  
 NCLS: 523/169.000; 523/435.000; 525/113.000; 525/121.000  
 IC [5]  
 ICM: C08L063-00  
 ICS: C08L027-18  
 EXF 523/169; 523/435; 525/113; 525/121; 427/386  
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L9 ANSWER 6 OF 6 USPATFULL on STN

Full Text	Citing References
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AN 87:78024 USPATFULL  
 TI Thermosettable **heat**-resistant resin compositions  
 IN Saito, Yasuhisa, Osaka, Japan  
 Takagishi, Hisao, Kyoto, Japan  
 Watanabe, Katsuya, Osaka, Japan  
 Okuno, Kohichi, Osaka, Japan  
 Kenmei, Junichi, Hyogo, Japan  
 Kamio, Kunimasa, Osaka, Japan  
 PA Sumitomo Chemical Company, Limited, Osaka, Japan (non-U.S. corporation)  
 PI US 4705833 19871110  
 AI US 1985-813272 19851224 (6)  
 PRAI JP 1985-7017 19850117  
 JP 1985-58966 19850323  
 DT Utility  
 FS Granted  
 LN.CNT 596  
 INCL INCLM: 525/504.000  
 INCLS: 525/423.000; 528/099.000; 528/108.000; 528/109.000; 528/113.000; 528/117.000; 528/322.000  
 NCL NCLM: 525/504.000  
 NCLS: 525/423.000; 528/099.000; 528/108.000; 528/109.000; 528/113.000; 528/117.000; 528/322.000  
 IC [4]  
 ICM: C08G059-44  
 ICS: C08G059-54  
 EXF 528/113; 528/117; 528/322; 528/363; 528/99; 528/108; 528/109; 525/423; 525/504  
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

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